

MINI LOW PROFILE CERAMIC SURFACE MOUNT MICROPROCESSOR CRYSTALS

ABM7



6.0 X 3.3 X 1.2

FEATURES:

- Low in height (1.3 mm max.)
- Ceramic package assures high reliability.
- Small size SMD, suitable for high density applications.
- Superior heat-resistant glass sealing.

APPLICATIONS:

- Computers, Modems, Communication equipment.
- Thin equipment

STANDARD SPECIFICATIONS:

PARAMETERS	
Frequency Range	10.00 MHz - 50.00 MHz
Operation Mode	Fundamental AT
Operating Temperature	-10°C to + 70°C (see options)
Storage Temperature	- 40°C to + 85°C
Frequency Tolerance @ 25°C	± 50 ppm max. (see options)
Frequency Stability over Temp.	± 50 ppm max. (see options)
Equivalent Series Resistance (ESR)	60Ω max. for 10.0MHz ≤ F < 16.0MHz
	50Ω max. for 16.0MHz ≤ F < 50.0MHz
Shunt Capacitance C ₀	7pF max.
Load Capacitance C _L	18pF (see options)
Drive Level	100μW max., 10μW correlation
Aging at 25°C First Year	± 5ppm max.
Insulation Resistance	500MΩ min. @ 100Vdc ± 15V

NOTES:

- Environmental, and mechanical specifications, see appendix C. Group 2.
- Marking, see appendix G.
- Tape and Reel, see appendix H.(1,000 pcs/reel)
- Recommended handling, see appendix F.
- Reflow profile, see appendix E.
- Application notes, see appendix A.

OPTIONS AND PART IDENTIFICATION (Left blank if standard):

ABM7 - Frequency - CL - ESR - Temperature - Tolerance - Stability - Packaging

XX.XXXX MHz

Load cap. in pF
or -S for Series

RXXX (value in Ω)

- 4 for ±30ppm max
- 2 for ±20ppm max

- B for -20°C to +70°C
- C for -30°C to +70°C
- N for -30°C to +85°C**
- D for -40°C to +85°C**

- Y for ± 25 ppm max.*
- H for ± 35 ppm max.*
- Z for ± 100 ppm max.#

-T for (Tape & Reel)

* standard temperature only.

** + 100 ppm only.

Option Z may apply to extended temperatures.

OUTLINE DRAWING:

